L Number		Search Text (polymeric polyimide polymer poymide) near4 substrate	DB USPAT; US-PGPUE; EPO; JPC;	Time stamp 2003/02/24 09:13
2	502	<pre>:/polymeric polyimide polymer poymide: near4 substrate' and trace near4 substrate;</pre>	DERWENT USEAT; USEATS ESC; JPC; DEEWENT	2003/02/24 09:14
3	169	(polymeric polyimide polymer poymide) near4 substrate) and (trace near4 substrate); and 257/\$6.cols.	USEAT; USEAT; USEPGPUE; ESC; JPC; DESWENT	2003/02/24 09:27
4	82	<pre>(((polymeric polyimide polymer poymide) near4 substrate) and (trace near4 substrate)) and (MCM (multi-chip near module) (multi near chip near module))</pre>	USFAT; US-PGPUE; EFC; JPC; DEFWENT	2003/02,24 09:46
5	21442	Yoshimura.in.	USEAT; US-EGPUE; ESI; JPI; DESWENT	2003/32/24 99:46
ć	1810	Yoshimura.in. and optical	USEAT; US-PGPUB; ESO; JPO; DESWENT	2003/02,24 69:47
7	40	(Yoshimura.in. and optical) and polymeric	USEAT; US-PGPUE; EFO; JPO; DEFWENT	2003/02/24 09:47
-	36	<pre>(polymeric polyimide polymer polymide) same (routing route) same trace same (chip die)</pre>	USFAT;	2003/02/13 10:46
-	426	"routing element"	USEAT; US-PGPUE; ESC; JPC; DEFWENT	1005/02.15 10:51
-	20	("routing element" and (chip die)) and trace	USEAT; US-PGPUE; EFO; JPO; DERWENT	2003/02/13 10:52
-	117	"routing element" and (chip die)	USEAT; US-PGPUE; EEO; JPO; DESWENT	2003/02/13 10:58
-	97	("routing element" and (chip die)) not (("routing element" and (chip die)) and trace)	USFAT; US-PGPUB; EFG; JPG; DERWENT	2003/02/18 11:01
-	2879	2577723	USPAT; US-PGPUE; EEC; JPO; DEEWENT	2003/02/13 11:01
-	1917	250×686	USFAT; USFEGEUB; EFO; UFO; DERWENT	2/03/12/13/11:41
-	888	2517.665	USFAT; US-PGEUB; EFO; JFD; DERWENT	78888 N. 18 (11) N.
-		CENTUTO	UPPAT; UPPEGETUR; EDD; TEP; DUSWENT	-2 -
-	2		COPAT; COMPSECS; EEO; JFO; DERMENT	

-	1948	287/M64	USPAT; US-PGPUB;	2003/02/13 11:02
-	2047	157/796	EPO; JPO; LERWENT USPAT; US-PGEUE;	2003/02/13 11:02
-	1537	260,891	EPO; JPC; DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/00/13 11:02
-	9396	287/723 257/686 257/685 257/777 257/730 287/784 287/786 257/691	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/02/13 10:11
-	2829	(257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691; and (polymeric polymide polymer)	DEFWENT USEAT; US-PGPUE; EFC; JPO;	2003/02/13 11:13
-	846	(:257/723 257/686 257/685 257/777 257/730 257/784 257/786 257,691) and (polymeric polymide polymide polymer)) and trace	DEFMENT USEAT; USEPGPUB; EPG; JPG; DBFWENT	2003/02/13 11:13
-	258	(((257/723 257/686 157/685 257/777 257/730 257/784 257/786 257,691) and (polymeric polymide polymer,) and trace)	USFAT; US-PGPUB; EFC; JPO;	2003/02/13 11:19
-	115	and route routing) (:(:257/723 257/686 257/685 257/777 257/733 257/784 257,786 257/691) and (polymeric polymide polymide polymer)) and trace) and (route routing)) and (bond	DEFWENT USFAT; US-PGPUB; EFC; JPO; DEFWENT	2003/02/13 11:25
-	3	near pad) "6420789"	USEAT; US-PGPUB; EPC; JPG;	2003/02/13 14:46
-	ę	"6522018"	DEFWENT USPAT; US-PGPUB; EEC; JPC;	2003/30/13 14:50
-	13	pershelle	DEFWENT USFAT; US-PGPUB; BPC; JPG;	2003/02/13 14:52
-	Û	perchelle	DEFWENT	2000/02/18 14:62
-	Ĉ	perschelle	DEFMENT USFAT; USFEGDUB; EFO; UFO;	2003/02/13 14:62
-	42e	"routing element"	DERWENT USEAT; USEGEUP; EEU; UFO;	2318+02/19/15:14
-	14	"routing element" and substrate and trace	DERWENT USEAT; USEPGEUB; EFO; JFO;	2003/02/19 15:16
-		substrate nearb trace and bond near pad	DERWENT USPAT; UL-ESPUP; EFO; (FO);	2 18 18123
-	. "'	winstrate near trace and boninear gad and only die semiconductor near device	IFFWENT TOFAT; TOFFFFFF; EFO; TEO; DERWENT	

-	54949	"wiring board"	UMBAT; US-PGPUB;	2003.00 09 05:36
-	316 3	"wiring board" and carrier	EPG; JPO; DERWENT USPAT; US-FGFUB; EPG; JPG;	2003/02/19 15:86
-	A51	"wiring board" and carrier and trace routs:	DERWENT TOFAT; MO-FORTH; EPO; JEN;	2003/02/29 25:36
-	lŝć	"wiring board" and carrier, and strace rout\$3); and (bond near pad)	DEFWENT USPAT; US-FGPUB; EPG; JPO; DERWENT	_www.ve_v21_19+0+
-	ģ3ga	((multi near chip) multichip) near5 module	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 09:11
-	1688	<pre>multi near chip; multichip, nearb mcdule, and trace and (chip die (semiconductor near device))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2103/31/21 09:13
-	617	<pre>((((multi near chip) multichip) near5 mcdule) and trace and (chip die (semiconductor near device))) and (bond near pad)</pre>	USPAT; US-PGPUB; EPG; JPG; DERWENT	2003/02/20 10:54
-	422	<pre>(f(((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polymide polym\$4 polyim\$4)</pre>	USPAT; US-PGPUH; EPG; JPO; DERWENT	2003/02/20 10:56
-	404	<pre>(;((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device).) and (bond near pad)) and (polymeric polymer polyimide polymide polym\$4 polyim\$4)) and</pre>	USPAT; US-PGPUB; EPO; UFO; DERWENT	2003/02/20 11:23
-	116	substrate ((((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polymide polymide polymide) and substrate) and rout\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 11:24